

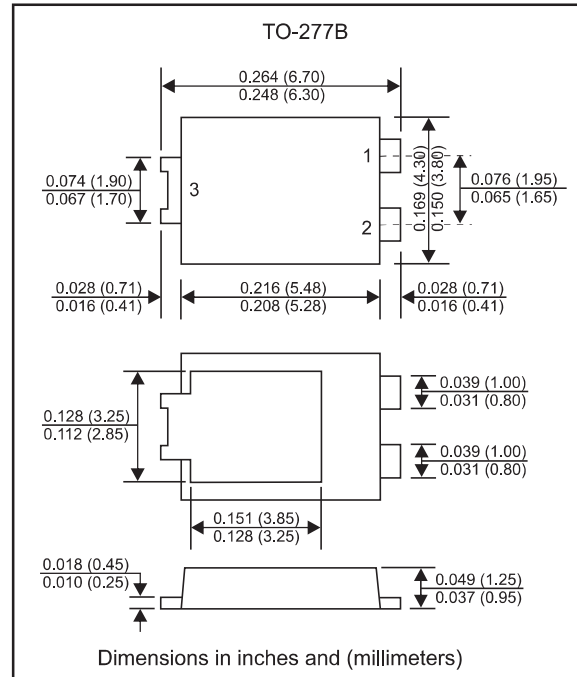
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

Mechanical data

- ◆ **Case:** JEDEC TO-277B molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	FSV20100V	Unit
DC Blocking Voltage	V_{DC}	100	V
Working Peak Reverse Voltage	V_{RWM}		
Repetitive Peak Reverse Voltage	V_{RRM}		
RMS Reverse Voltage	V_{RMS}	70	V
Average Forward Rectified Current	$I_{F(AV)}$	20.0	A
Peak Forward Surge Current, 8.3ms Half Sine-wave ($T_A=25^\circ\text{C}$)	I_{FSM}	280	A
Operating junction temperature range	T_J	-55 to +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	MIN.	TYP.	MAX.	Unit
Reverse Breakdown Voltage	$I_R=0.1\text{mA}, T_J=25^\circ\text{C}$	V_B	100	-	-	V
Forward voltage	$I_F=20\text{A}, T_J=25^\circ\text{C}$	V_F			0.66	V
Reverse current	$V_R=100\text{V}, T_J=25^\circ\text{C}$	I_R			0.10	mA
	$V_R=100\text{V}, T_J=125^\circ\text{C}$				20	

Rating and characteristic curves

FIG. 1: Forward Output Current Derating Curve

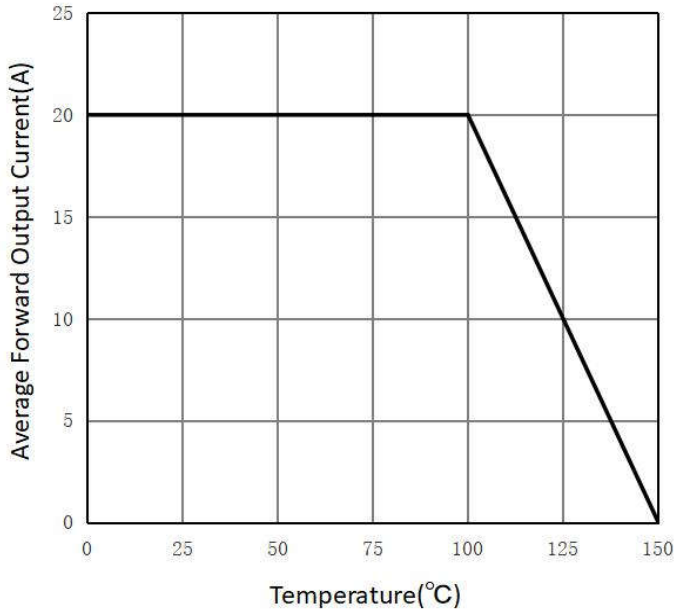


FIG. 2: Maximum Non-Repetitive Peak Forward Surge Current

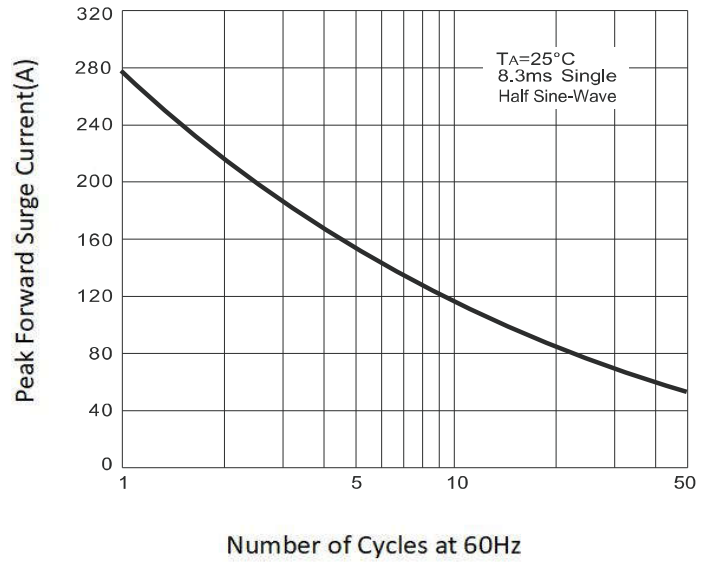


FIG. 3: Typical Forward Characteristics

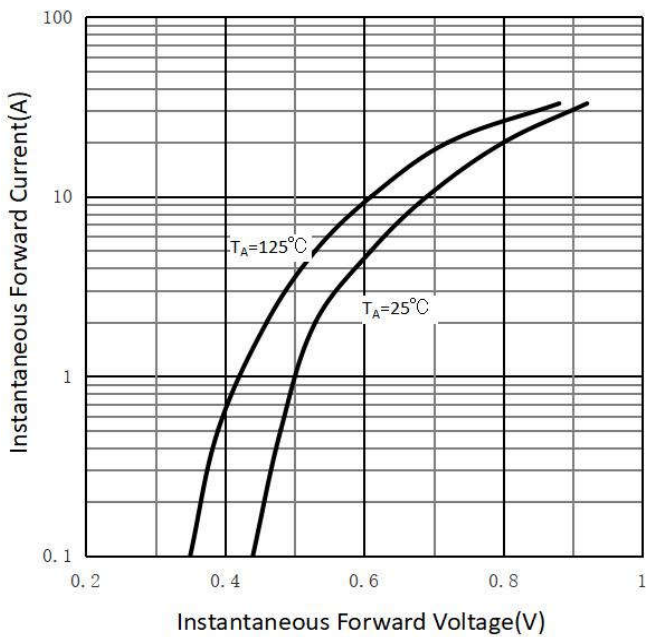
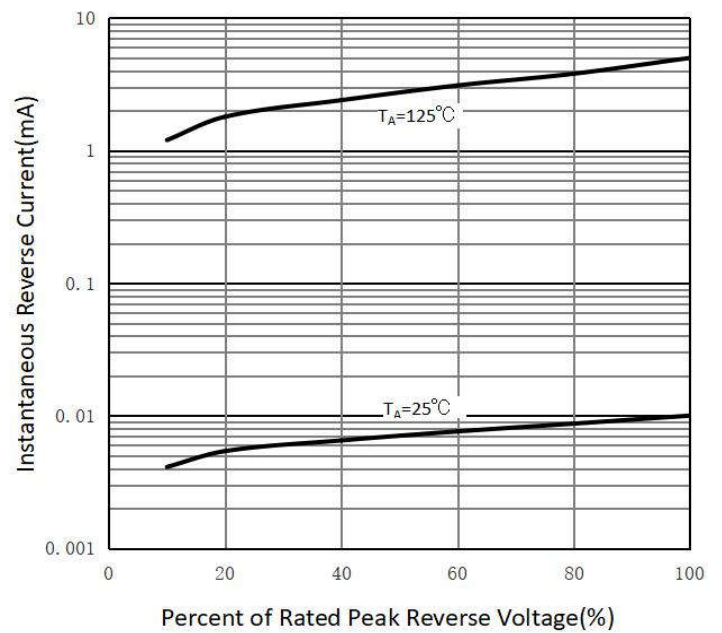


FIG. 4: Typical Reverse Characteristics



Pinning information

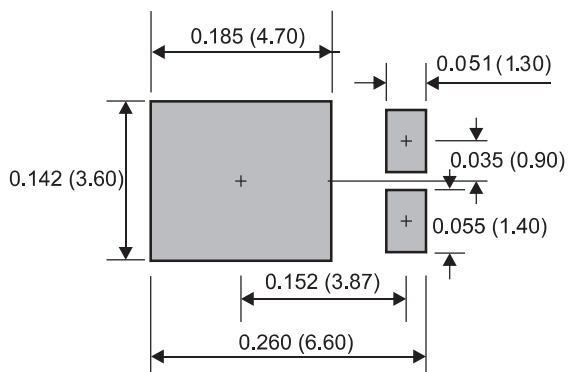
Pin	Simplified outline	Symbol
Pin3 cathode Pin1 anode Pin2 anode		

Marking

Type number	Marking code
FSV20100V	

Suggested solder pad layout

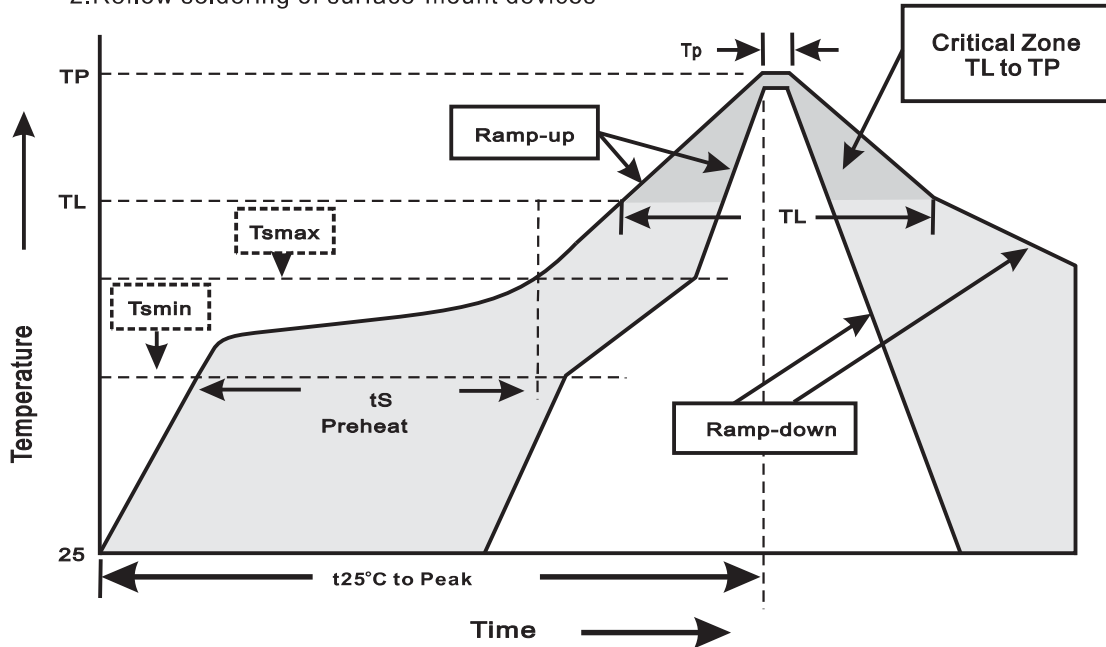
TO-277B



Dimensions in inches and (millimeters)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes